

Title (en)  
ELECTRIC CIRCUIT ARRANGEMENT

Title (de)  
ELEKTRISCHE SCHALTUNGSANORDNUNG

Title (fr)  
CIRCUIT ELECTRIQUE

Publication  
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Application  
**EP 04797703 A 20041108**

Priority  
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Abstract (en)  
[origin: WO2005053366A1] The invention relates to an electric circuit arrangement (1) comprising an interconnect device (2) that is equipped with a chip (3). Said interconnect device (2) contains a substrate (4), in which a receiving recess (5) is configured that is closed on all sides. First contact pads that are connected to printed conductors (6) are provided on the base. Said pads are electrically connected to second contact pads (17) of the chip (3) that is positioned above the first pads by the interposition of a contact element (24) that is an anisotropic electric conductor and simultaneously elastically deformable. A force exertion structure that is fixed to the substrate (4) exerts a force on the upper face of the chip (3) to produce the contact pressure required for the establishment of electrical contact.

IPC 8 full level  
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